

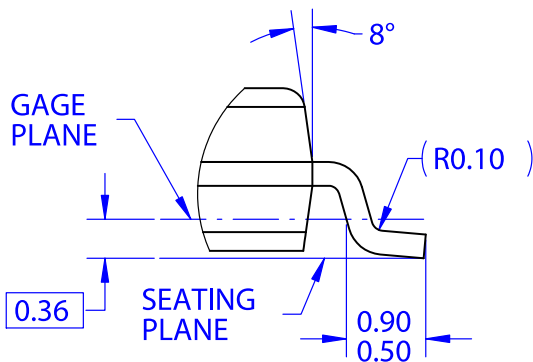
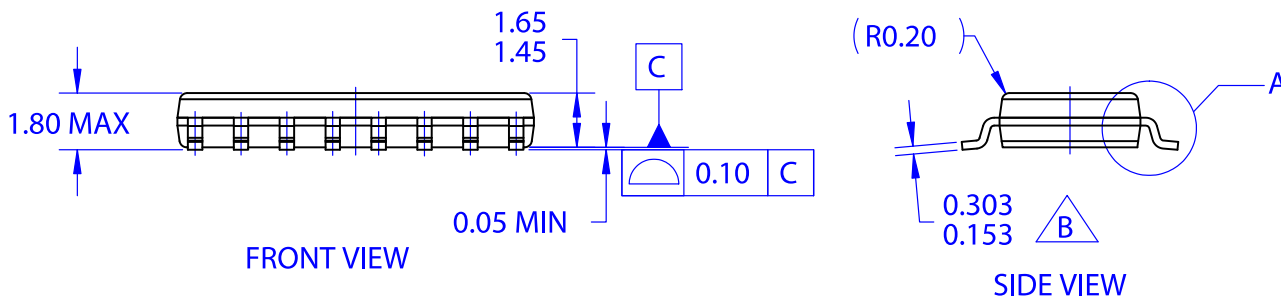
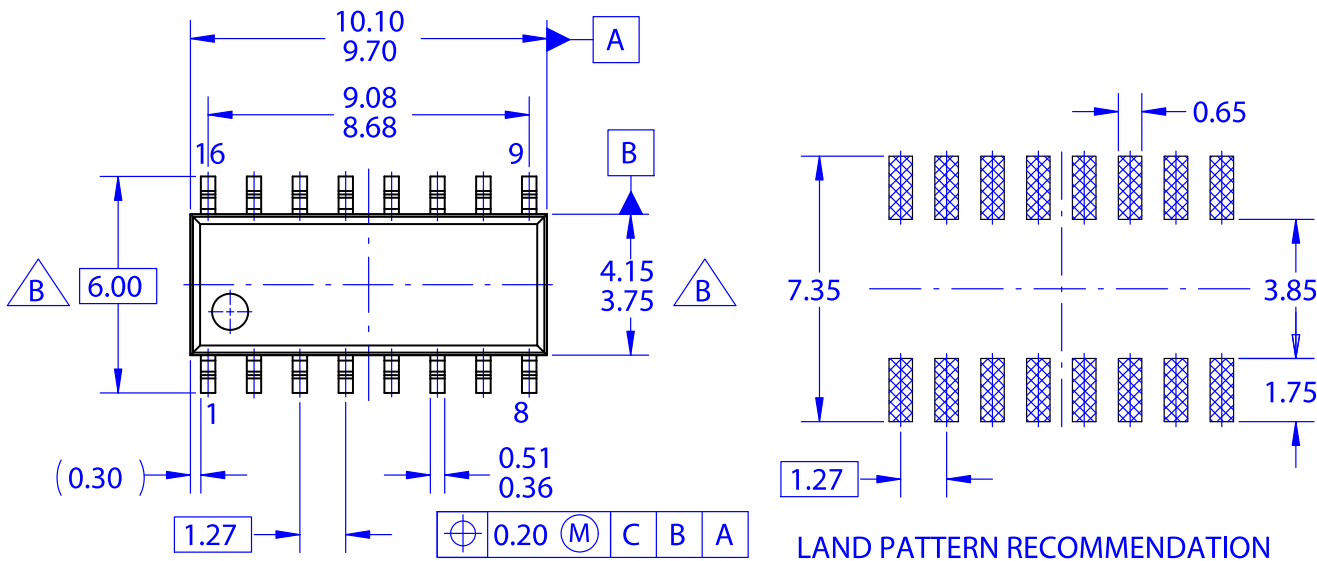
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

ON Semiconductor®



**SOIC16 N**  
**CASE 751ES**  
**ISSUE O**

DATE 31 DEC 2016



**NOTES:**

- A. THIS DRAWING COMPLIES WITH JEDEC MS-012, EXCEPT AS NOTED
- B. THIS DIMENSION IS OUTSIDE JEDEC MS-012 VALUE
- C. ALL DIMENSIONS ARE IN MILLIMETERS
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS

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<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>SOIC16 N</b>	<b>PAGE 1 OF 2</b>

